

SNx4AC245 3 ステート出力、オクタル・バス・トランシーバ

1 特長

- 2V~6V の V_{CC} で動作
- 6V までの入力電圧に対応
- 最大 t_{pd} 7ns (5V 時)

2 アプリケーション

- 業務用オーディオ
- ビデオとサイネージ
- 家電製品
- ファクトリ・オートメーション / 制御

3 概要

'AC245 オクタル バス トランシーバは、データ バス間の非同期双方向通信用に設計されています。制御機能を実装しているため、外部のタイミング要件は最小限です。

このデバイスを使うと、方向制御 (DIR) 入力の論理レベルに応じて、A バスから B バス、または B バスから A バスへデータを転送できます。出カインープル (OE) 入力を使うと、本デバイスを無効化してバスを実質的に絶縁できます。

製品情報

部品番号	パッケージ (1)	パッケージサイズ (2)	本体サイズ (3)
SNx4AC245	DB (SSOP, 20)	7.2mm × 7.8mm	7.2mm × 5.3mm
	DGS (VSSOP, 20)	5.1mm × 4.9mm	5.1mm × 3mm
	DW (SOIC, 20)	12.8mm × 10.3mm	12.8mm × 7.5mm
	N (PDIP, 20)	24.33mm × 9.4mm	24.33mm × 6.35mm
	NS (SO, 20)	12.6mm × 7.8mm	12.6mm × 5.3mm
	PW (TSSOP, 20)	6.5mm × 6.4mm	6.5mm × 4.4mm
	RKS (VQFN, 20)	4.5mm × 2.5mm	4.5mm × 2.5mm

- (1) 詳細については、[セクション 11](#) を参照してください。
- (2) パッケージサイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。
- (3) 本体サイズ (長さ × 幅) は公称値であり、ピンは含まれません。

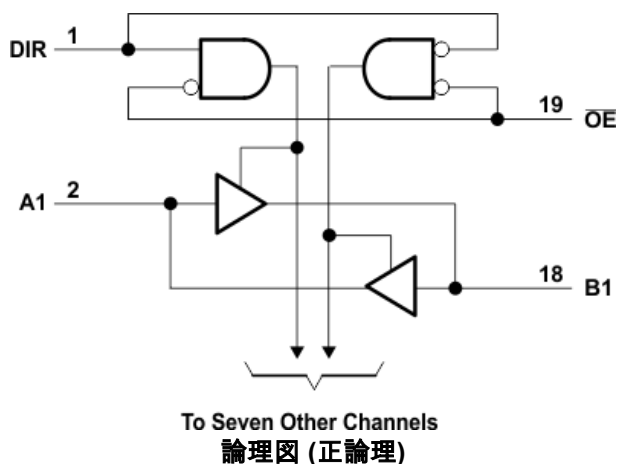
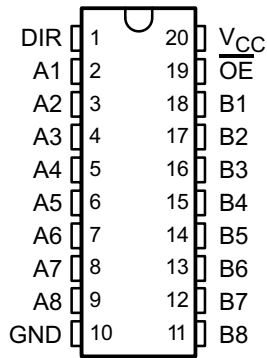



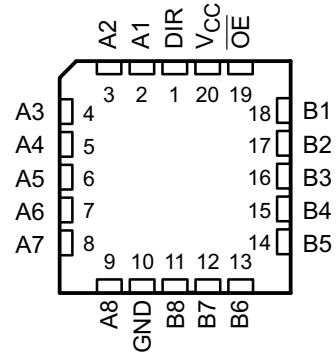
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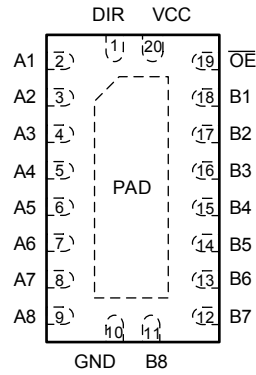
4 Pin Configuration and Functions




4-1. SN54AC245 J or W Package; SN74AC245 DB, DGS, DW, N, NS, or PW Package Top View




4-2. SN54AC245 FK Package Top View




4-3. SN54AC245 RKS Package Top View

Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NO.	NAME		
1	DIR	I/O	Direction Pin
2	A1	I/O	A1 Input/Output
3	A2	I/O	A2 Input/Output
4	A3	I/O	A3 Input/Output
5	A4	I/O	A4 Input/Output
6	A5	I/O	A5 Input/Output
7	A6	I/O	A6 Input/Output
8	A7	I/O	A7 Input/Output
9	A8	I/O	A8 Input/Output
10	GND	—	Ground Pin
11	B8	I/O	B8 Input/Output
12	B7	I/O	B7 Input/Output
13	B6	I/O	B6 Input/Output
14	B5	I/O	B5 Input/Output
15	B4	I/O	B4 Input/Output
16	B3	I/O	B3 Input/Output
17	B2	I/O	B2 Input/Output
18	B1	I/O	B1 Input/Output
19	OE	I/O	Output Enable
20	VCC	—	Power Pin

(1) Signal Types: I = Input, O = Output, I/O = Input or Output

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage	-0.5 V to V _{CC} + 0.5 V	-0.5	7	V
V _I	Input voltage ⁽²⁾	-0.5 V to V _{CC} + 0.5 V			V
V _O	Output voltage ⁽²⁾	-0.5 V to V _{CC} + 0.5 V			V
I _{IK}	Input clamp current	V _I < 0 or V _I > V _{CC}		±20	mA
I _{OK}	Output clamp current	V _O < 0 or V _O > V _{CC}		±20	mA
I _O	Continuous output current	V _O = 0 to V _{CC}	-65	±50	mA
	Continuous current through V _{CC} or GND			±200	mA
T _{stg}	Storage temperature		-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		SN54AC245		SN74AC245		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	2	6	2	6	V
V _{IH}	High-level input voltage	V _{CC} = 3 V	2.1	2.1		V
		V _{CC} = 4.5 V	3.15	3.15		
		V _{CC} = 5.5 V	3.85	3.85		
V _{IL}	Low-level input voltage	V _{CC} = 3 V		0.9	0.9	V
		V _{CC} = 4.5 V		1.35	1.35	
		V _{CC} = 5.5 V		1.65	1.65	
V _I	Input voltage	0	V _{CC}	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 3 V		-12	-12	mA
		V _{CC} = 4.5 V		-24	-24	
		V _{CC} = 5.5 V		-24	-24	
I _{OL}	Low-level output current	V _{CC} = 3 V		12	12	mA
		V _{CC} = 4.5 V		24	24	
		V _{CC} = 5.5 V		24	24	
t/v	Input transition rise or fall rate		8		8	ns/V

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		SN54AC245		SN74AC245		UNIT
		MIN	MAX	MIN	MAX	
T _A	Operating free-air temperature	-55	125	-40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SNx4AC245							UNIT
		DB (SSOP)	DGS (VSSOP)	DW (SOIC)	N (PDIP)	NS (SOP)	PW (TSSOP)	RKS (VQFN)	
		20 PINS							
R _{θJA}	Junction-to-ambient thermal resistance	70	123.5	98.6	69	60	126.6	67.7	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AC245		SN74AC245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	3 V	2.9			2.9	2.9		V	
		4.5 V	4.4			4.4	4.4			
		5.5 V	5.4			5.4	5.4			
	I _{OH} = -12 mA	3 V	2.56			2.4	2.46			
		4.5 V	3.86			3.7	3.76			
	I _{OH} = -24 mA	4.5 V	4.86			4.7	4.76			
		5.5 V				3.85				
V _{OL}	I _{OL} = 50 μA	3 V	0.002 0.1		0.1	0.1		V		
		4.5 V	0.001 0.1		0.1	0.1				
		5.5 V	0.001 0.1		0.1	0.1				
	I _{OL} = 12 mA	3 V	0.36		0.5	0.44				
		4.5 V	0.36		0.5	0.44				
	I _{OL} = 24 mA	4.5 V	0.36		0.5	0.44				
		5.5 V	0.36		0.5	0.44				
I _{OL} = 50 mA ¹	5.5 V			1.65						
I _I	A or B ports ² OE or DIR	V _I = V _{CC} or 0	5.5 V	±0.1		±1	±1		μA	
				±0.1		±1	±1			
I _{OZ}	V _O = V _{CC} or GND, V _I (OE) = V _{IL} or V _{IH}	5.5 V	±0.5		±10	±5		μA		
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V	4		80	40		μA		
C _i	V _I = V _{CC} or GND	5 V	4.5					pF		
C _{io}	V _O = V _{CC} or GND	5 V	15					pF		

- Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
- For I/O ports, the parameter IOZ includes the input leakage current.

5.6 Switching Characteristics, $V_{CC} = 3.3\text{ V } 0.3\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted)
(see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC245		SN74AC245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.5	5	8.5	1	11.5	1	9	ns
t_{PHL}			1.5	5	8.5	1	10	1	9	
t_{PZH}	\overline{OE}	A or B	2.5	7	11.5	1	13.5	2	12.5	ns
t_{PZL}			2.5	7.5	12	1	14.5	2	13.5	
t_{PHZ}	\overline{OE}	A or B	2	6.5	12	1	13.5	1	12.5	ns
t_{PLZ}			2	7	11.5	1	14	1.5	13	

5.7 Switching Characteristics, $V_{CC} = 5\text{ V } 5\text{ V}$

over recommended operating free-air temperature range (unless otherwise noted)
(see [セクション 6](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC245		SN74AC245		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	B or A	1.5	3.5	6.5	1	8.5	1	7	ns
t_{PHL}			1.5	3.5	6	1	7.5	1	7	
t_{PZH}	\overline{OE}	A or B	1.5	5	8.5	1	10	1	9	ns
t_{PZL}			1.5	5.5	9	1	10.5	1	9.5	
t_{PHZ}	\overline{OE}	A or B	1.5	5.5	9	1	10.5	1	10	ns
t_{PLZ}			1.5	5.5	9	1	10.5	1	10	

5.8 Operating Characteristics

$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance per transceiver	$CL = 50\text{ pF}$, $f = 1\text{ MHz}$	45	pF

5.9 Typical Characteristics

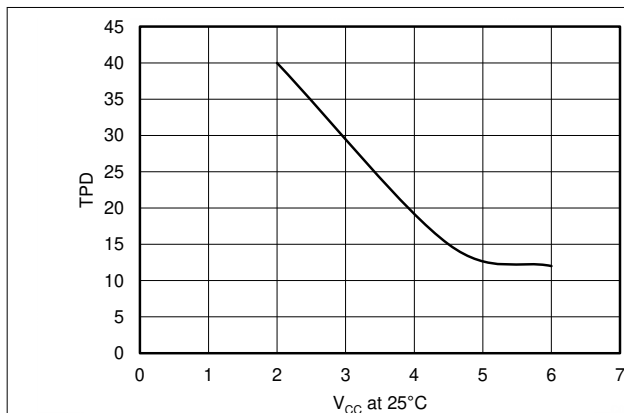


図 5-1. TPD vs V_{CC} at 25°C

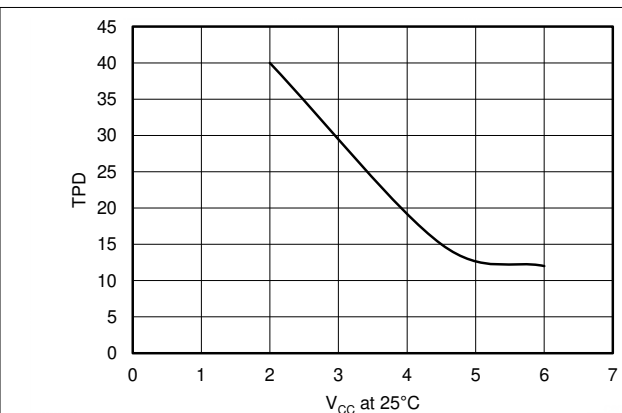
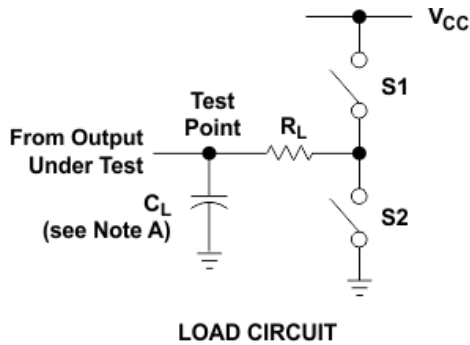
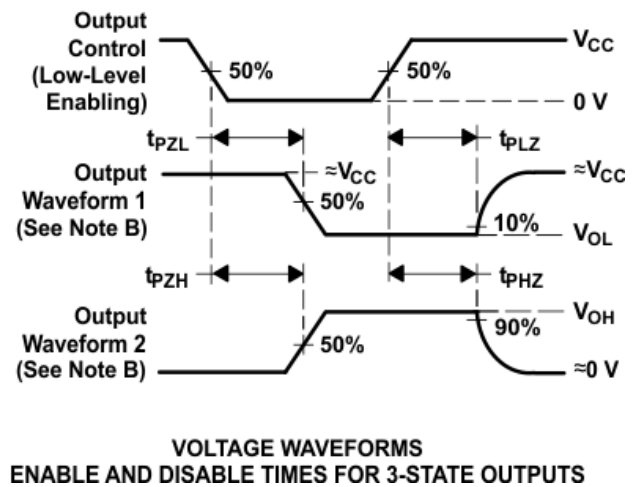
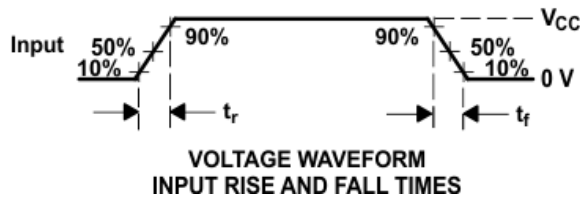
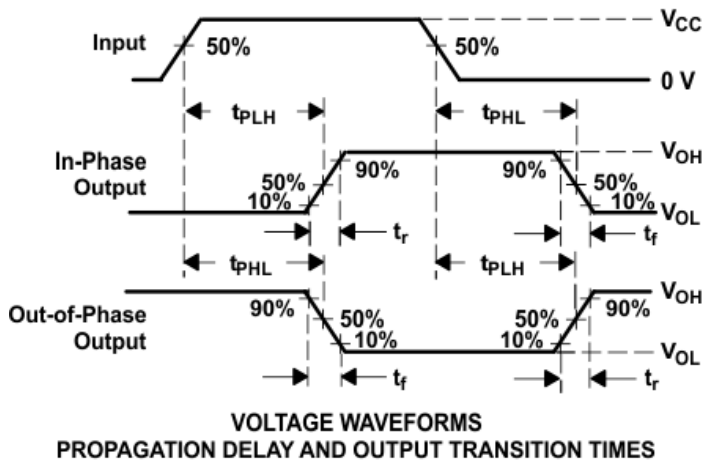


図 5-2. TPD vs V_{CC} at 25°C

6 Parameter Measurement Information



PARAMETER		R_L	C_L	S1	S2
t_{en}	t_{pZH}	1 k Ω	50 pF or 150 pF	Open	Closed
	t_{pZL}			Closed	Open
t_{dis}	t_{pHZ}	1 k Ω	50 pF	Open	Closed
	t_{pLZ}			Closed	Open
t_{pd} or t_t		--	50 pF or 150 pF	Open	Open

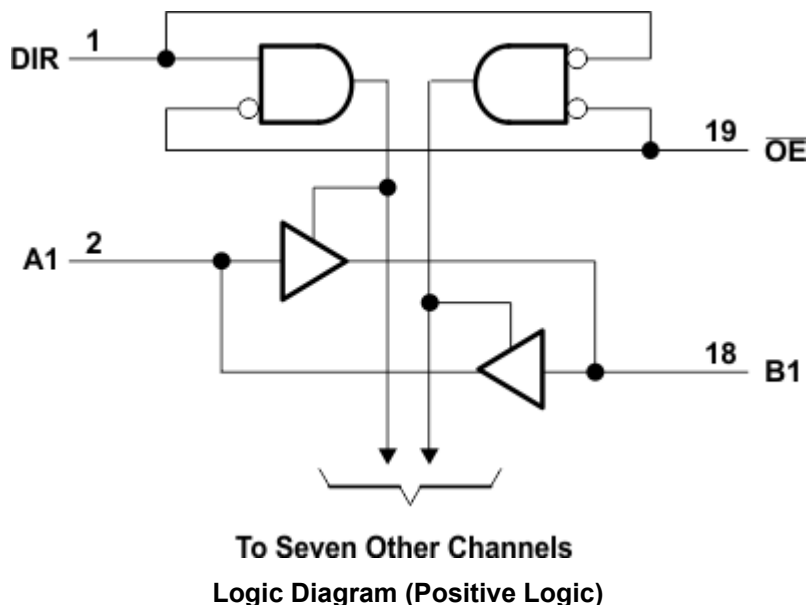


7 Detailed Description

7.1 Overview

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements. The SNx4AC245 devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so that the buses are effectively isolated. To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

7.2 Functional Block Diagram



7.3 Feature Description

The SNx4AC245 devices have a wide operating V_{CC} range from 2 V to 6 V with slower edge rates to minimize output ringing.

7.4 Device Functional Modes

表 7-1 lists the function modes of the SNx4AC245.

表 7-1. Function Table

INPUTS ⁽¹⁾		OPERATION
OE	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

(1) H = High Voltage Level, L = Low Voltage Level, X = Don't Care

8 アプリケーション情報に関する免責事項

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

8.1 Application Information

The SNx4AC245 is a low-drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs.

8.2 Typical Application

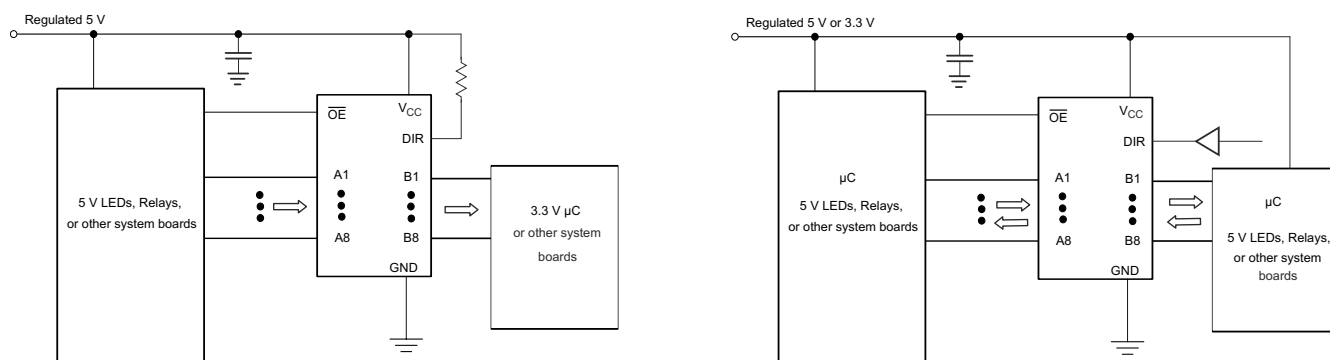


図 8-1. Typical Application Schematic

8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. Outputs can be combined to produce higher drive but the high drive will also create faster edges into light loads, so routing and load conditions should be considered to prevent ringing.

8.2.2 Detailed Design Procedure

- Recommended Input Conditions
 - Rise time and fall time specs: See $(\Delta t/\Delta V)$ in the [セクション 5.3](#).
 - Specified high and low levels: See $(V_{IH}$ and $V_{IL})$ in the [セクション 5.3](#).
- Recommend Output Conditions
 - Load currents should not exceed 25 mA per output and 75 mA total for the part.
 - Outputs should not be pulled above V_{CC} .

8.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [セクション 5.3](#).

Each V_{CC} pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 μF is recommended; if there are multiple V_{CC} pins, then 0.01 μF or 0.022 μF is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 μF and a 1 μF are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

8.4 Layout

8.4.1 Layout Guidelines

When using multiple-bit logic devices, inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. [セクション 8.4.2](#) specifies the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} , whichever makes more sense or is more convenient. It is generally acceptable to float outputs, unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the output section of the part when asserted. This will not disable the input section of the IOs, so they cannot float when disabled.

8.4.2 Layout Example

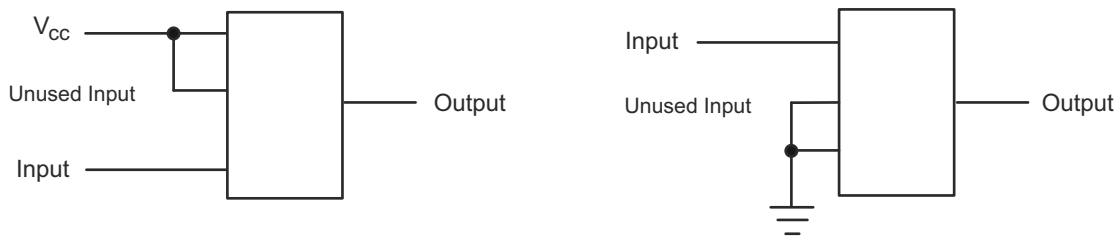


図 8-2. Layout Diagram

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

表 9-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54AC245	Click here	Click here	Click here	Click here	Click here
SN74AC245	Click here	Click here	Click here	Click here	Click here

9.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

9.3 サポート・リソース

[テキサス・インスツルメンツ E2E™ サポート・フォーラム](#) は、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

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9.4 Trademarks

テキサス・インスツルメンツ E2E™ is a trademark of Texas Instruments.
すべての商標は、それぞれの所有者に帰属します。

9.5 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

9.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision H (March 2024) to Revision I (April 2024) Page

- Updated thermal values for RθJA: DW = 58 to 98.6, PW = 83 to 126.6, all values in °C/W 6

Changes from Revision G (January 2023) to Revision H (March 2024) Page

- 「製品情報」表、「ピン構成および機能」セクション、および「熱に関する情報」表に DGS および RKS パッケージを追加 1

- 「パッケージ情報」を「製品情報」に変更し、表にパッケージ サイズを追加..... [1](#)
-

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87758012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-87758012A SNJ54AC 245FK	Samples
5962-8775801RA	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8775801RA SNJ54AC245J	Samples
5962-8775801SA	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8775801SA SNJ54AC245W	Samples
SN74AC245DBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC245	Samples
SN74AC245DGSR	ACTIVE	VSSOP	DGS	20	5000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC245	Samples
SN74AC245DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 85	AC245	
SN74AC245DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC245	Samples
SN74AC245DWRE4	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC245	Samples
SN74AC245N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC245N	Samples
SN74AC245NE4	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC245N	Samples
SN74AC245NSR	ACTIVE	SOP	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC245	Samples
SN74AC245PW	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI	-40 to 85	AC245	
SN74AC245PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC245	Samples
SN74AC245RKSR	ACTIVE	VQFN	RKS	20	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC245	Samples
SNJ54AC245FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-87758012A SNJ54AC 245FK	Samples
SNJ54AC245J	ACTIVE	CDIP	J	20	20	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8775801RA SNJ54AC245J	Samples
SNJ54AC245W	ACTIVE	CFP	W	20	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8775801SA SNJ54AC245W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of ≤ 1000 ppm threshold. Antimony trioxide based flame retardants must also meet the ≤ 1000 ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54AC245, SN74AC245 :

● Catalog : [SN74AC245](#)

● Automotive : [SN74AC245-Q1](#), [SN74AC245-Q1](#)

● Enhanced Product : [SN74AC245-EP](#), [SN74AC245-EP](#)

- Military : [SN54AC245](#)
- Space : [SN54AC245-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

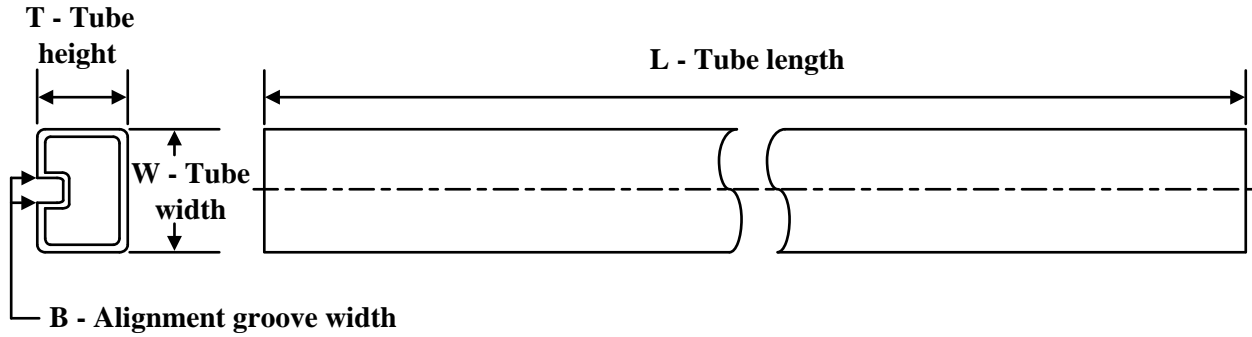

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC245DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AC245DGSR	VSSOP	DGS	20	5000	330.0	16.4	5.4	5.4	1.45	8.0	16.0	Q1
SN74AC245DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74AC245DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74AC245NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AC245PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74AC245PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74AC245RKSR	VQFN	RKS	20	3000	180.0	12.4	2.8	4.8	1.2	4.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC245DBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74AC245DGSR	VSSOP	DGS	20	5000	353.0	353.0	32.0
SN74AC245DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AC245DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74AC245NSR	SOP	NS	20	2000	367.0	367.0	45.0
SN74AC245PWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74AC245PWR	TSSOP	PW	20	2000	356.0	356.0	35.0
SN74AC245RKSR	VQFN	RKS	20	3000	210.0	185.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-87758012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8775801SA	W	CFP	20	25	506.98	26.16	6220	NA
SN74AC245N	N	PDIP	20	20	506	13.97	11230	4.32
SN74AC245NE4	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54AC245FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AC245W	W	CFP	20	25	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

PW0020A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220206/A 02/2017

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

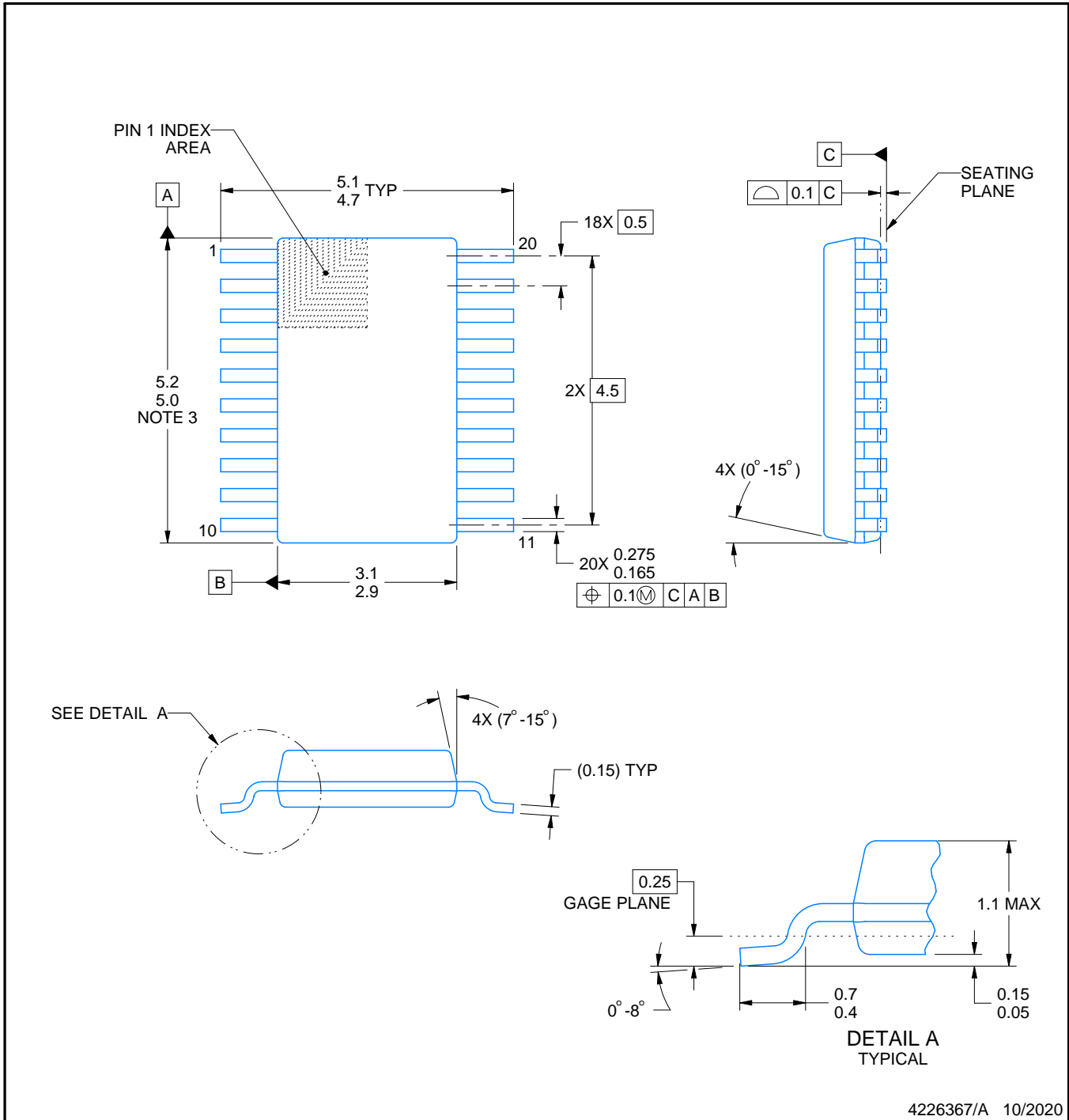
DGS0020A



PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



NOTES:

PowerPAD is a trademark of Texas Instruments.

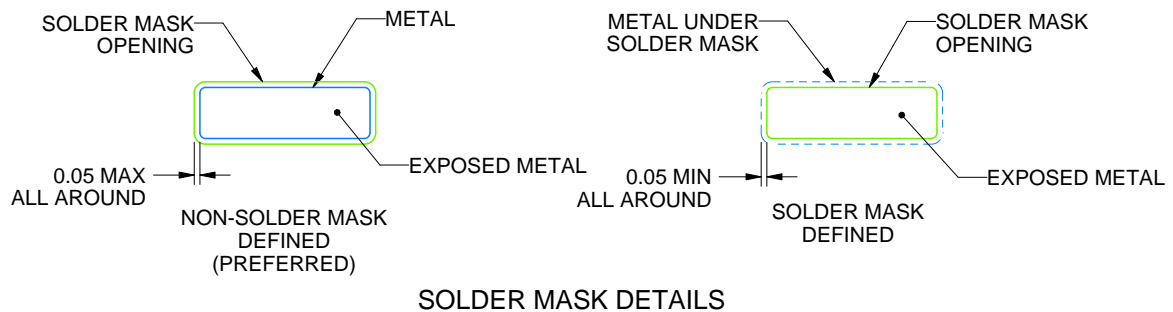
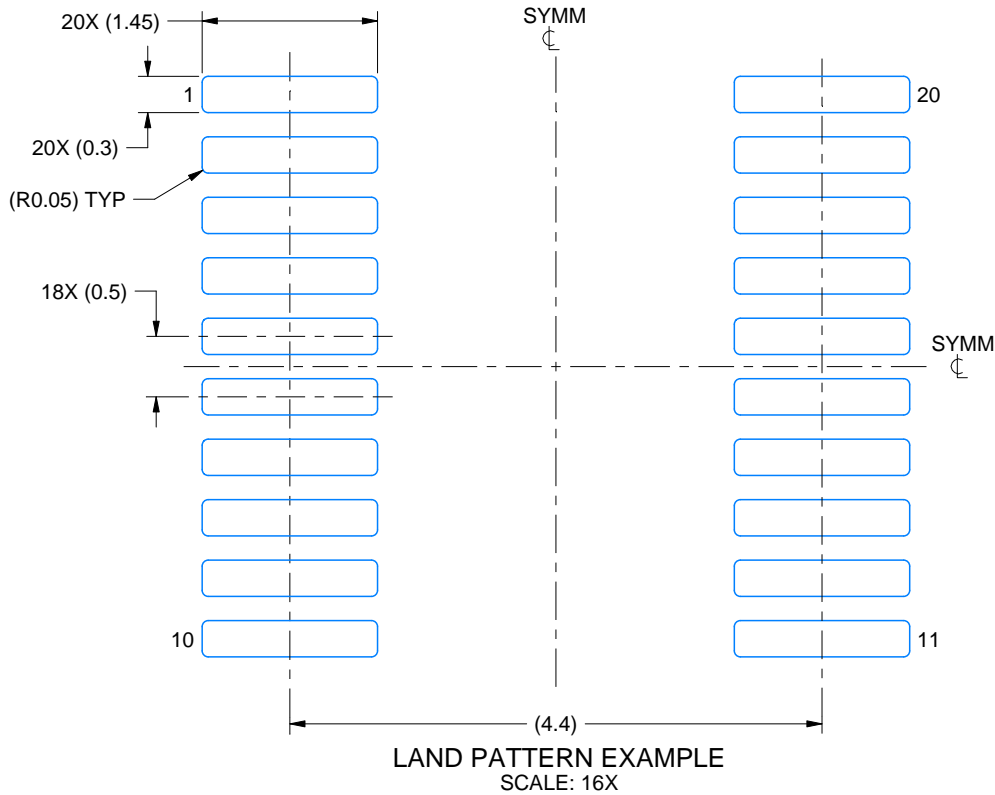
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of September 2020.
5. Features may differ or may not be present.

EXAMPLE BOARD LAYOUT

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4226367/A 10/2020

NOTES: (continued)

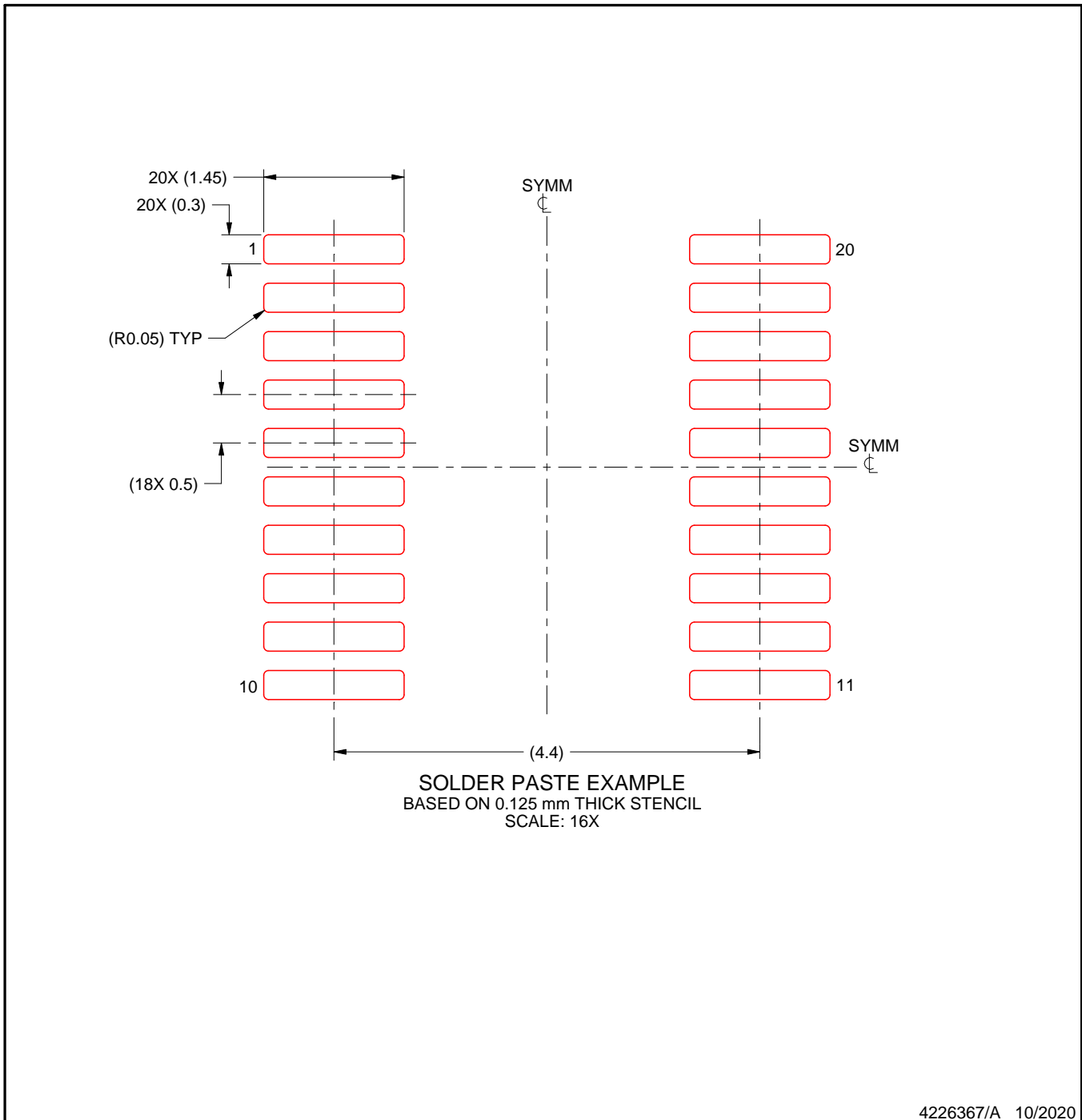
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

DB0020A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4214851/B 08/2019

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

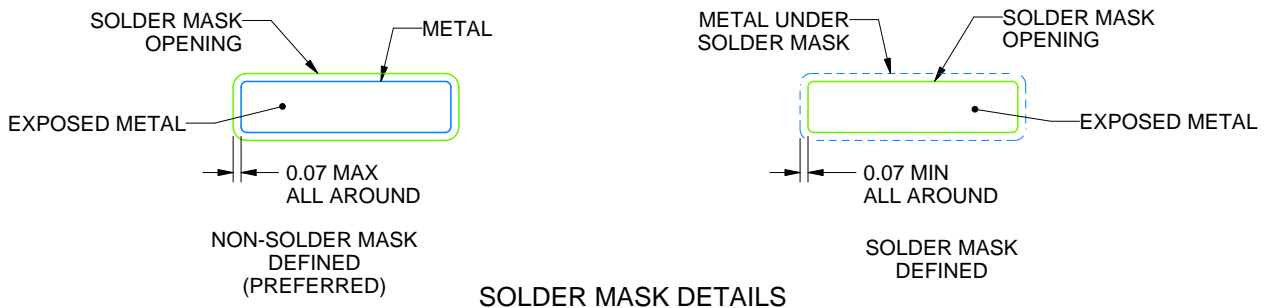
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4214851/B 08/2019

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

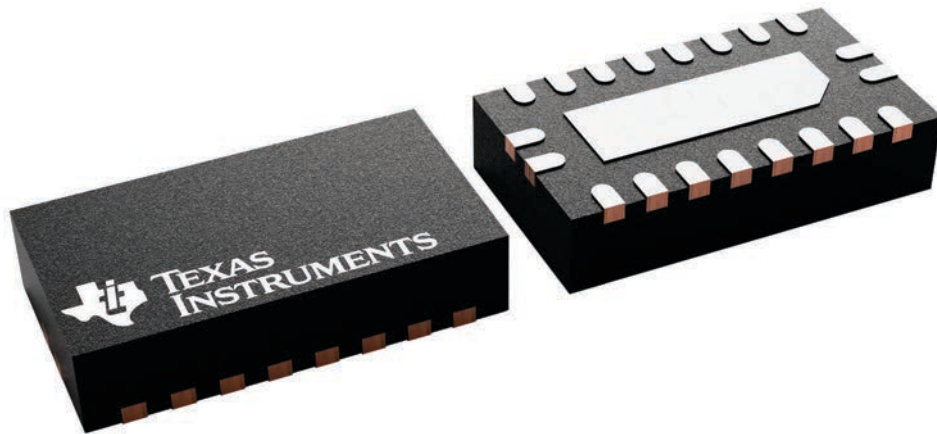
RKS 20

VQFN - 1 mm max height

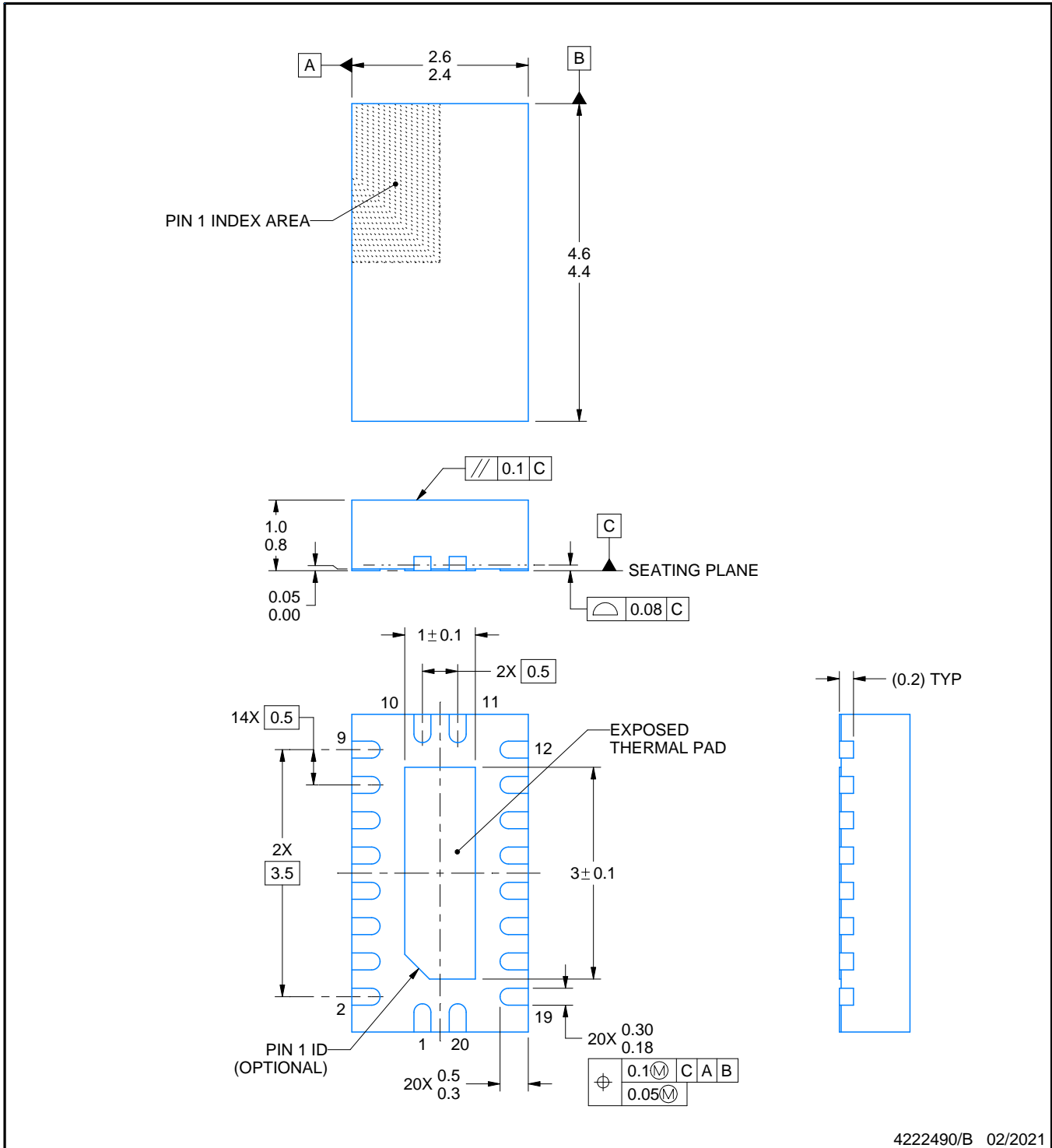
2.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4226872/A



NOTES:

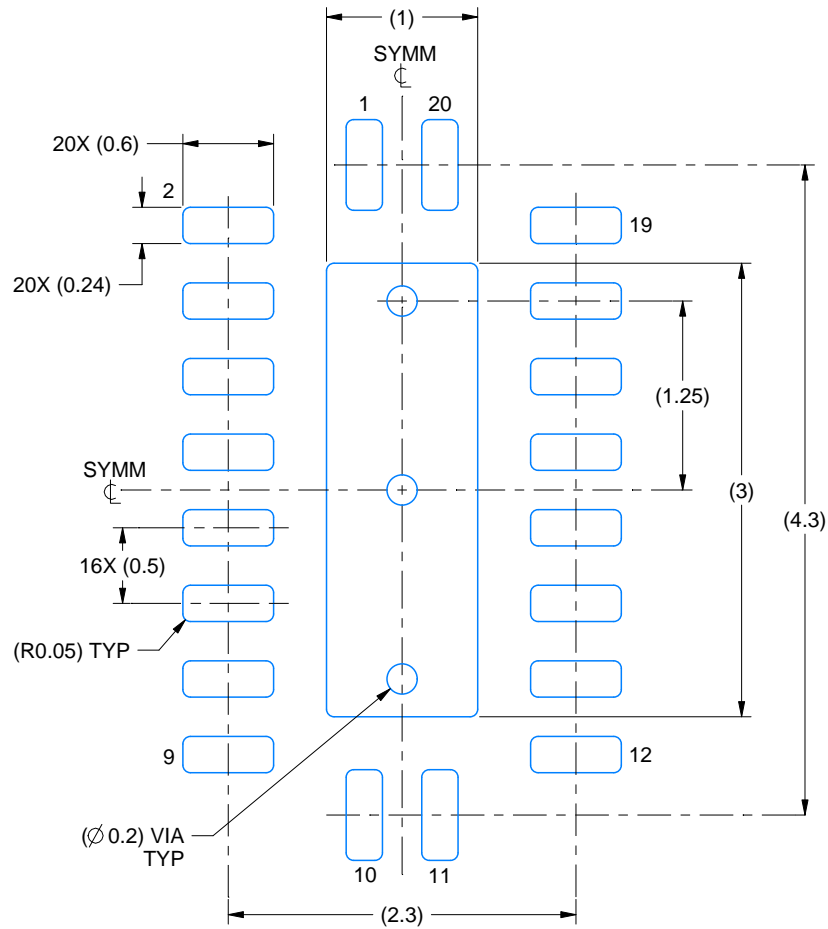
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

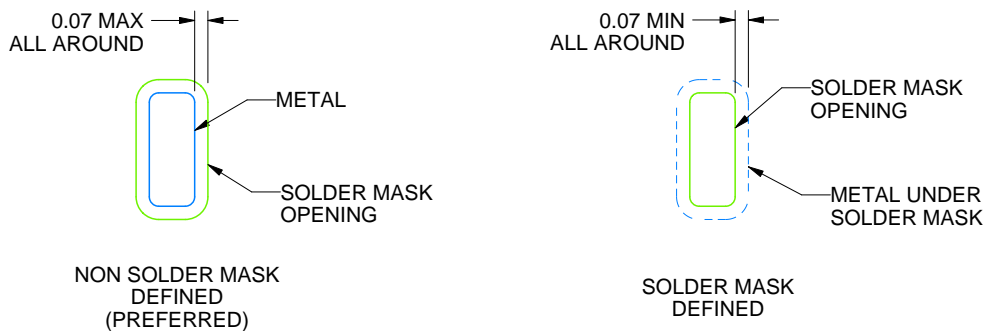
RKS0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
SCALE:20X



SOLDER MASK DETAILS

4222490/B 02/2021

NOTES: (continued)

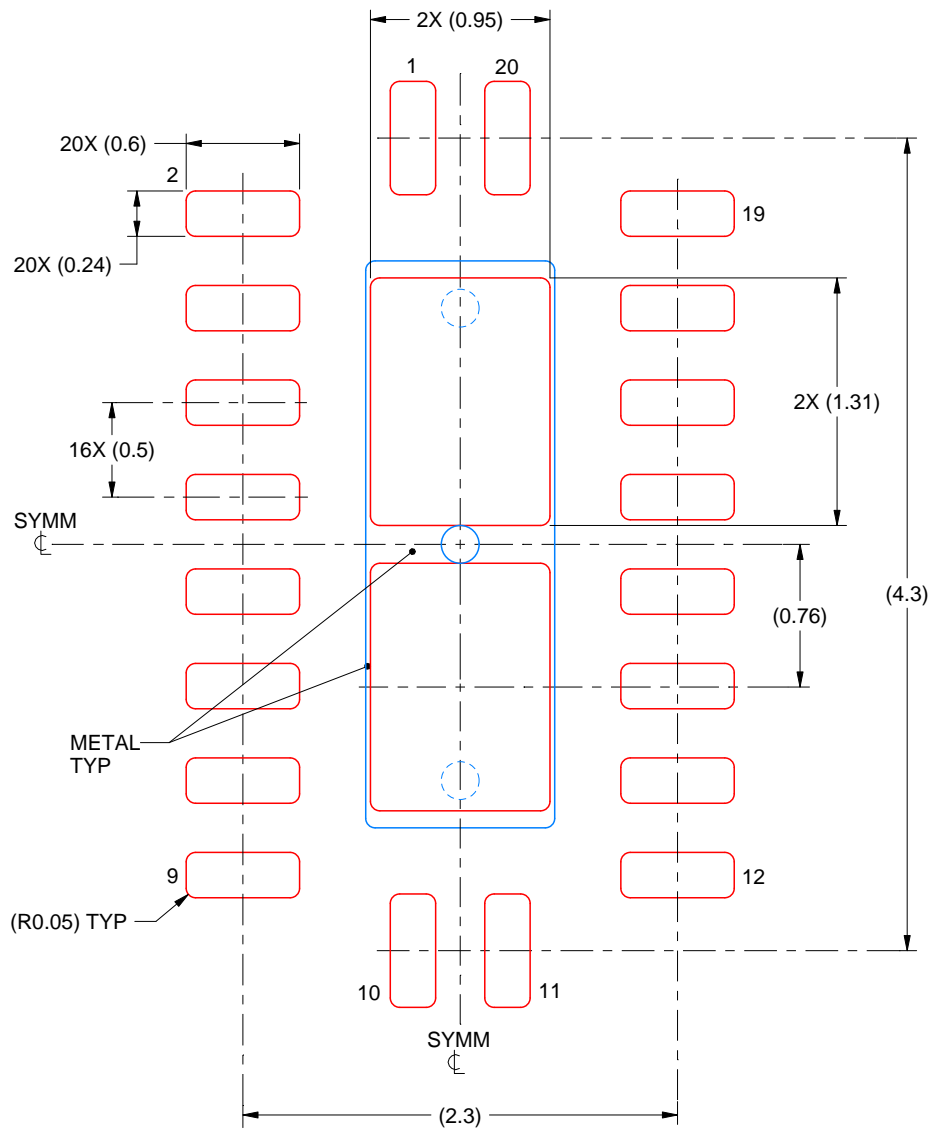
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
- Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

EXAMPLE STENCIL DESIGN

RKS0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
 83% PRINTED SOLDER COVERAGE BY AREA
 SCALE:25X

4222490/B 02/2021

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

GENERIC PACKAGE VIEW

FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4229370VA\

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

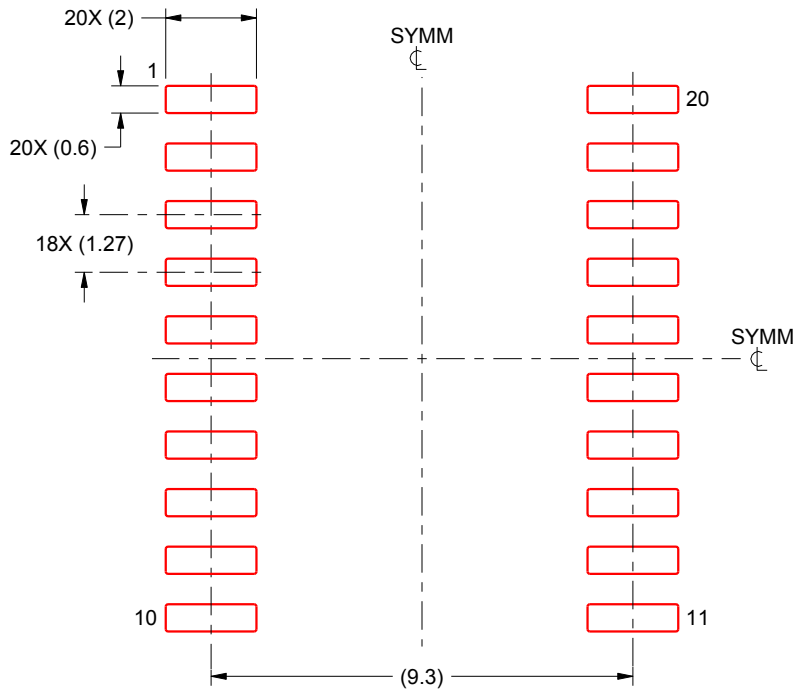
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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